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प्लाज़्मा अनुसंधान संस्थान
INSTITUTE FOR PLASMA RESEARCH
परमाणु ऊर्जा विभाग, भारत सरकार का एक सहायता



प्राप्त संस्थान
An Aided Institute of Department of Atomic Energy,
Government of India

इन्दिरा पुल के पास, भट, गांधीनगर - 382 428 भारत
दूरभाष: (079) 2396 2020/2021/2028
फैक्स: 91-079-23962277
वेब: www.ipr.res.in

NEAR INDIRA BRIDGE, BHAT
DIST. GANDHINAGAR - 382 428 (INDIA)
Phone: (079) 2396 2020/2021/2028
Fax : 91-079-23962277
Web : www.ipr.res.in

ENQUIRY

ENQUIRY NO : IPR/EQL/19-20/082
Date : 29-05-2019

Due on : 01-08-2019 by 1:00 PM IST

Reminder-1 Dt: 28-06-2019

Please send your offer in sealed envelope specifying Enquiry No, Date & Due Date, ALONG WITH your credentials for the following items:

Important Note:

Please note that e-mail quotations are not acceptable however you may send your queries (if any) to localpurchase@ipr.res.in

Please ensure your sealed quotation reaches this office not later than above mentioned due date and time.

Kindly go through the following documents properly before quoting which are available on the IPR web portal i.e., http://www.ipr.res.in/documents/tender_terms.html / attached herewith.

- 1) Instructions to the bidders & Terms and conditions (refer Form No: **IPR-LP-01.V4**)
- 2) Bidding format

GST for Goods and Services (IGST/CGST/SGST TAX BENEFITS): Please refer **clause no: 8** of Form No: **IPR-LP-01.V4**

QUOTATION SHOULD BE ADDRESSED TO PURCHASE OFFICER ONLY

Sr No	Description	Quantity
1	Card Frame chassis S20 4U/84T/480mmD with accessories as per the attached specification.	4.0 Nos.

2	4U/10T/227mmD Plug In modules with accessories as per the attached specification.	32.0 Nos.
3	Card Frame S20 3U/84T/480mmD with accessories as per the attached specification.	6.0 Nos.
4	3U/10T/227mmD Plug In modules with accessories as per the attached specification.	48.0 Nos.

Note: TDS as per CGST Act: As per provisions of section No. 51 of the CGST Act 2017, TDS @2% (IGST 2% or CGST 1% and SGST 1%) will be deducted while making payment to the suppliers where total value of orders/contracts/work orders exceeds Rs. 2.5 lakhs, in the event of order in Indian Rupees. Necessary TDS Certificate will be issued to the supplier after TDS deduction.

Encl: As Per Attachment

Sd/-

Mr. D. Ramesh
Purchase Officer-II

Information to Vendors: We are working towards a single platform for our future requirement. Hence, please refer IPR website i.e, <http://www.ipr.res.in/documents/tenderseng.html> for our future requirement.

Indent Specifications

Item No. 01	Card Frame S20 3U/84T/480mmD chassis
Qty	6

Specifications for Card frame chassis and components (for one set)

Sr no.	Description	Qty	UNIT
1	Card Frame S20 3U/84T/480mmD with following specifications and accessories(For one chassis)	6	Nos.
	1. Material : Aluminum with natural anodized finish		
	2. Side Panels of 14 SWG (2 mm) Thick with Locating Holes at 15 mm depth intervals		
	3. Rear Panel 2.5 mm thick with Downward opening with hinges		
	4. Top and Bottom cover as per card frame size		
	5. Front Profiles with threaded strips to fit PIM in the card frames		
	6. Rear profiles with threaded strips should be suitable for direct mounting of motherboards without necessity of insulation Spacers.		
	7. One Extra profile required on bottom plate at 300 mm for mounting of Power supply card.		
	8. Card guides to mount 10T PIM as per specified depth		
	9. Extra Facia of 4T for covering open space with one card guide.		
	10. Pull out Handles		
	11. Also Quote if any other basic accessory required		

Item No. 02	3U/10T/227mmD Plug In modules
Qty	48 (Set of below mentioned all items)

Specifications for 3U size Plug in Modules and components

Sr no.	Description	Qty	UNIT
1	3U/10T/227mmD Plug In modules with following specifications and accessories	48	Nos.
	1. Material : All Aluminum construction with natural anodized finish		
	2. Front facia plate with no cutouts and mentioned quantity.		
	3. Rear Panel with standard Euro-96 pin slot to fit into the mother board PCB.		
	4. All side plates should be plain (No Slotting, X=0).		
	5. All top and bottom plates should be vented or with holes for air-circulation.		

Note : Vendor has to demonstrate fixing of IPR motherboard in card frame and fixing of PIM cards on motherboard without any misalignment.
Contact IPR in case of any clarification required.

Item No. 01	Card Frame chassis S20 4U/84T/480mmD
Qty	4(Set of below mentioned all items)

Specifications for Card frame chassis and components (for one set)

Sr no.	Code	Description	Qty
1	Special	<p>Card Frame chassis S20 4U/84T/480mmD with following specifications and ccessories</p> <ol style="list-style-type: none"> 1. Material : Aluminum with natural anodized finish 2. Side Panels of 14 SWG (2 mm) Thick with Locating Holes at 15 mm depth intervals 3. Rear Panel 2.5 mm thick with Downward opening with hinges 4. Top and Bottom cover as per card frame size 5. Front Profiles with threaded strips to fit PIM in the card frames 6. Rear profiles with threaded strips should be suitable for direct mounting of motherboards without necessity of insulation Spacers. 7. Card guides to mount 10T PIM as per specified depth 8. Extra Facia of 4T for covering open space with one card guide. 9. Pull out Handles 10. One extra profile required on bottom plate at 300mm for mounting 11. Also Quote if any other basic accessory required 	4

Item No. 02	4U/10T/227mmD Plug In modules
Qty	32 (Set of below mentioned all items)

Specifications for Plug in Modules and components (One set)

Sr no.	Code	Description	Qty
1	Special	<p>4U/10T/227mmD Plug In modules with following specifications and accessories</p> <ol style="list-style-type: none"> 1. Material : All Aluminum construction with natural anodized finish 2. Front facia plate with no cutout and mentioned quantity. (Exact Drawing with all dimensions will be provided at the time of placing order) 3. Rear Panel with standard Euro slot to fit into the mother board 4. All side plates should be plain (No Slotting, X=0) 5. All top and bottom plates should be vented or with holes for air-circulation. 	32

Note :

Vendor has to demonstrate fixing of IPR motherboard in card frame and fixing of PIM cards on motherboard without any misalignment.

Contact IPR in case of any clarification required.